

METHOD FOR CONSTRUCTING A WAFER-INTERPOSER ASSEMBLY

ABSTRACT OF THE DISCLOSURE

A method for reducing the likelihood of damaging a semiconductor wafer (18) and the integrated circuit chips of the semiconductor wafer (18) during handling utilizes a wafer interposer (12) having a wafer receiving portion (28) and a handling portion (30). The wafer receiving portion (28) of the wafer interposer (12) has a plurality of contact pads (22) that are electrically and non-temporarily mechanically connected to the contact pads of the integrated circuit chips of the wafer (18). The handling portion (30) of the wafer interposer (12) extends outwardly from the wafer receiving portion (28) such that the handling portion (30) is accessible to handling equipment without the handling equipment contacting the attached wafer (18).